



BSS127

### N-CHANNEL ENHANCEMENT MODE FIELD MOSFET

# **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub>	Package	I <sub>D</sub> T <sub>A</sub> = +25°C
600V	160Ω @ V <sub>GS</sub> = 10V	SC59 SOT23	70mA

### **Description**

This new generation uses advanced planar technology MOSFET, provide excellent high Voltage and fast switching, making it ideal for small-signal and level shift applications.

# **Applications**

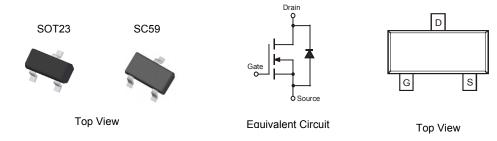
- Motor Control
- Backlighting
- DC-DC Converters
- Power Management Functions

# **Features**

- Low Input Capacitance
- High BVDss rating for power application
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

### **Mechanical Data**

- Case: SC59 / SOT23
- Case Material: Molded Plastic "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Weight: 0.008 grams (approximate)



### **Ordering Information** (Note 4)

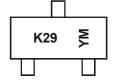
Part Number	Case	Packaging
BSS127SSN-7	SC59	3000/Tape & Reel
BSS127S-7	SOT23	3000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

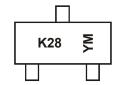
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.

# **Marking Information**





K29 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: W = 2009) M = Month (ex: 9 = September)



K28 = Product Type Marking Code YM = Date Code Marking

SC59

Y = Year (ex: W = 2009) M = Month (ex: 9 = September)

Date Code Key

Year	200	9	2010		2011	20	12	2013		2014	2	2015
Code	W		Х		Υ		Z	Α		В		С
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	$V_{DSS}$	600	V		
Gate-Source Voltage			V <sub>GSS</sub>	±20	V
Continuous Drain Current (Note 5) V <sub>GS</sub> = 10V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	50 40	mA
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	70 55	mA
Continuous Drain Current (Note 5) V <sub>GS</sub> = 5V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	45 35	mA
Continuous Drain Current (Note 6) V <sub>GS</sub> = 5V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	65 50	mA
Pulsed Drain Current @ T <sub>SP</sub> = +25°C (Notes 7)			I <sub>DM</sub>	0.16	Α

# **Thermal Characteristics**

Characteristic	Symbol	Value	Units
Power Dissipation, @T <sub>A</sub> = +25°C (Note 5)	$P_{D}$	0.61	W
Thermal Resistance, Junction to Ambient @ T <sub>A</sub> = +25°C (Note 5)	$R_{\theta JA}$	204	°C/W
Power Dissipation, @T <sub>A</sub> = +25°C (Note 6)	$P_{D}$	1.25	W
Thermal Resistance, Junction to Ambient @ T <sub>A</sub> = +25°C (Note 6)	$R_{\theta JA}$	100	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

# Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	600	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	_	_	0.1	μΑ	$V_{DS} = 600V, V_{GS} = 0V$	
Gate-Body Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	3	_	4.5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance		_	80	160	Ω	$V_{GS} = 10V, I_D = 16mA$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	95	190	12	$V_{GS} = 5.0V, I_D = 16mA$	
Forward Transfer Admittance	Y <sub>fs</sub>	_	76	_	mS	V <sub>DS</sub> = 10V, I <sub>D</sub> = 16mA	
Diode Forward Voltage	$V_{SD}$	_	_	1.5	V	$V_{GS} = 0V, I_{S} = 16mA$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C <sub>iss</sub>	_	21.8	_			
Output Capacitance	Coss	_	2.2	_	pF	$V_{DS} = 25V$ , $V_{GS} = 0V$ , $f = 1.0MHz$	
Reverse Transfer Capacitance	Crss	_	0.3	_			
Total Gate Charge	Qg	_	1.08	_		101/1/	
Gate-Source Charge	Q <sub>gs</sub>	_	0.08	_	nC	$V_{GS} = 10V, V_{DD} = 300V,$ $I_{D} = 0.01A$	
Gate-Drain Charge	$Q_{gd}$	_	0.50	_		ID = 0.01A	
Turn-On Delay Time	t <sub>D(on)</sub>	_	5.0	_	ns	.,	
Turn-On Rise Time	t <sub>r</sub>	_	7.2	_	ns	$V_{DD} = 300V, V_{GS} = 10V,$	
Turn-Off Delay Time	t <sub>D(off)</sub>	_	28.7	_	ns	$R_{GEN} = 6\Omega$	
Turn-Off Fall Time	t <sub>f</sub>	_	168	_	ns	I <sub>D</sub> = 10mA	
Reverse Recovery Time	T <sub>rr</sub>	_	131	_	ns	V <sub>R</sub> =300 V, I <sub>F</sub> =0.016 A,	
Reverse Recovery Charge	Q <sub>rr</sub>	_	32	_	nC	di/dt = 100A/µs	

Notes:

- 5. Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
  6. Device mounted on 1" x 1" FR-4 PCB with high coverage 2 oz. Copper, single sided.
  7. Repetitive rating, pulse width limited by junction temperature, 10µs pulse, duty cycle = 1%.
  8. Short duration pulse test used to minimize self-heating effect.
  9. Guaranteed by design. Not subject to production testing.

5

T<sub>A</sub> = 85°C

T<sub>A</sub> = 25°C

 $T_A = -55$ °C

V<sub>GS</sub>=10V,

I<sub>D</sub>=16mA

100

125

T<sub>A</sub>= 25°C

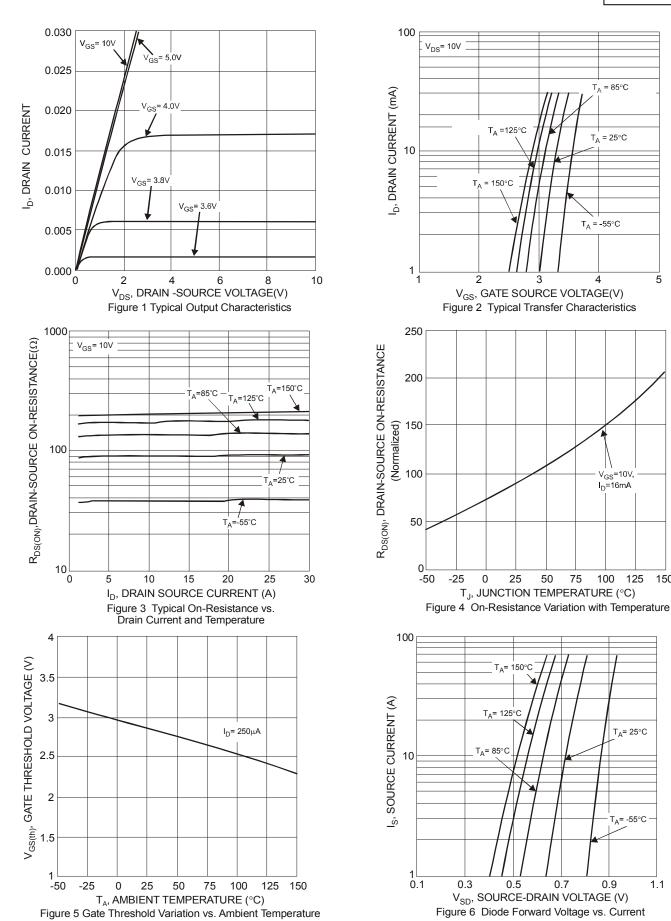
T<sub>A</sub>= -55°C

0.9

150

75





1.1



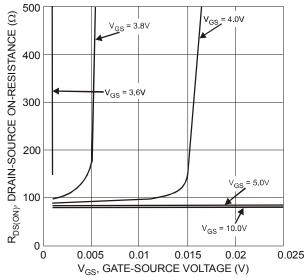


Figure 7 Typical On-Resistance vs. Drain Current and Gate Voltage

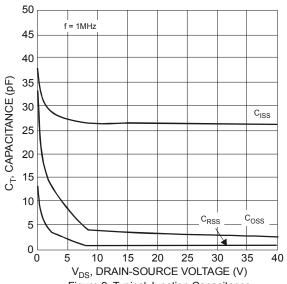
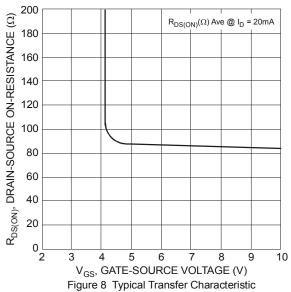


Figure 9 Typical Junction Capacitance



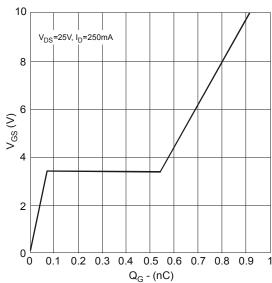


Figure 10 Gate Charge Characteristics

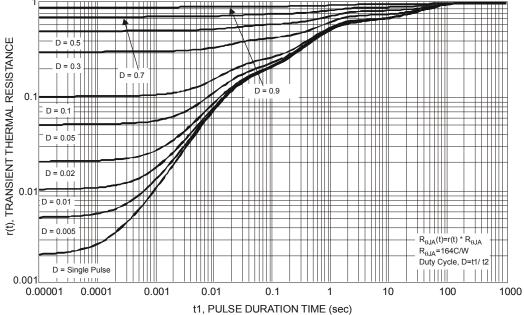


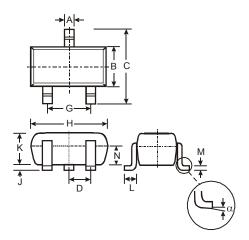
Figure 11 Transient Thermal Resistance



# **Package Outline Dimensions**

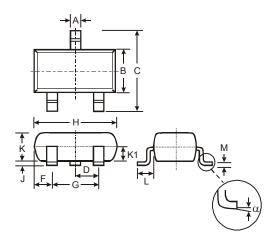
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

### **SC59**



	SC59						
Dim	Min	Max	Тур				
Α	0.35	0.50	0.38				
В	1.50	1.70	1.60				
C	2.70	3.00	2.80				
D	-	1	0.95				
G	-	-	1.90				
Н	2.90	3.10	3.00				
J	0.013	0.10	0.05				
K	1.00	1.30	1.10				
L	0.35	0.55	0.40				
М	0.10	0.20	0.15				
N	0.70	0.80	0.75				
α	0°	8°	-				
All	All Dimensions in mm						

### SOT23

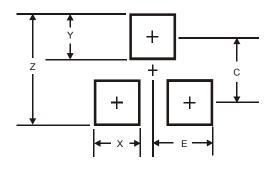


SOT23						
Dim	Min	Max	Тур			
Α	0.37	0.51	0.40			
В	1.20	1.40	1.30			
С	2.30	2.50	2.40			
D	0.89	1.03	0.915			
F	0.45	0.60	0.535			
G	1.78	2.05	1.83			
Н	2.80	3.00	2.90			
J	0.013	0.10	0.05			
K	0.903	1.10	1.00			
K1	-	1	0.400			
L	0.45	0.61	0.55			
M	0.085	0.18	0.11			
α	0°	8°	-			
All Dimensions in mm						

# Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

### **SC59**

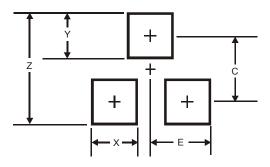


Dimensions	Value (in mm)
Z	3.4
Х	0.8
Y	1.0
С	2.4
Е	1.35



### Suggested Pad Layout (cont.)

### SOT23



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Y	0.9
С	2.0
E	1.35

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